



Material Content Data Sheet



Sales Product Name				6ED003L02-F2		Issued		20. July 2018	
MA#				MA001062994					
Package				PG-TSSOP-28-1		Weight*		107.03 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.034	2.84	2.84	28351	28351	
leadframe	non noble metal	nickel	7440-02-0	14.398	13.45		134517		
	non noble metal	iron	7439-89-6	19.882	18.58	32.03	185762	320279	
wire	noble metal	gold	7440-57-5	0.846	0.79	0.79	7906	7906	
encapsulation	organic material	carbon black	1333-86-4	0.194	0.18		1817		
	plastics	epoxy resin	-	8.231	7.69		76901		
	inorganic material	silicondioxide	60676-86-0	56.385	52.67	60.54	526806	605524	
leadfinish	non noble metal	tin	7440-31-5	1.539	1.44	1.44	14383	14383	
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13226	13226	
glue	plastics	acrylic resin	-	0.221	0.21		2066		
	noble metal	silver	7440-22-4	0.885	0.83	1.04	8265	10331	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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